	N Number:	2020051	9000	PCN Date:	May	21, 202	20
ītl	e: Datasheet f	or TLV3012	-Q1				
Cus	stomer Contact:	PCN Mana	ger		De	pt:	Quality Services
Cha	ange Type:						
	Assembly Site		Des	ign		Wafer	Bump Site
	Assembly Process		🛛 🛛 🛛 🖂	🔀 Data Sheet		Wafer Bump Material	
	Assembly Materials			Part number change		Wafer Bump Process	
	Mechanical Specification			Test Site		Wafer Fab Site	
	Packing/Shipping/Labeling		Test	Test Process		Wafer Fab Materials	
						Wafer	Fab Process
	scription of Chan		Notifi	cation Details			
The		t(s) is being	updated a	ing an information o as summarized belo er details.		otificatio	on. TLV3012-Q1
_					SBOS5	51A – MARC	H 2011-REVISED JUNE 2019
C	Changes from Original (I	March 2011) to	Revision A				Page
	grade						
		r will be cha	nging.			-	
	e datasheet numbe evice Family	r will be cha	nging.	Change From:		Chang	e To:
De		r will be cha	nging.	Change From: SBOS551		Chang SBOS5	
De TL' The http Rea To a Ant No a to t	evice Family V3012-Q1 ese changes may be o://www.ti.com/pro ason for Change: accurately reflect d ticipated impact anticipated impact he actual device.	e reviewed a oduct/TLV30 levice charac on Fit, Forr . This is a sp	at the data <u>12-Q1</u> cteristics. <b>n, Functi</b> pecification		i <b>abilit</b> y nent o	SBOS5	551A tive / negative)
De TL' The http Rea To a Ant No a to t Cha	evice Family V3012-Q1 ese changes may be c://www.ti.com/pro ason for Change: accurately reflect d ticipated impact he actual device. anges to product	e reviewed a oduct/TLV30 levice charac on Fit, Forr . This is a sp	at the data <u>12-Q1</u> cteristics. <b>n, Functi</b> pecification	SBOS551 asheet links provided on, Quality or Reli	i <b>abilit</b> y nent o	SBOS5	551A tive / negative)
De TL The http Rea To a Ant No a to t Cha Non Pro	evice Family V3012-Q1 ese changes may be o://www.ti.com/pro ason for Change: accurately reflect d ticipated impact anticipated impact he actual device.	e reviewed a oduct/TLV30 levice charac on Fit, Forr . This is a sp	at the data <u>12-Q1</u> cteristics. <b>n, Functi</b> pecification	SBOS551 asheet links provided on, Quality or Reli	i <b>abilit</b> y nent o	SBOS5	551A tive / negative)

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location

E-Mail

USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN ww admin team@list.ti.com

## IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (<u>www.ti.com/legal/termsofsale.html</u>) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.